

## N-Channel Enhancement Mode MOSFET

### 1. Product Information

#### 1.1 Features

- SGT Technology
- Low  $F_{OM}$   $R_{DS(ON)} \times Q_{gd}$

#### 1.2 Applications

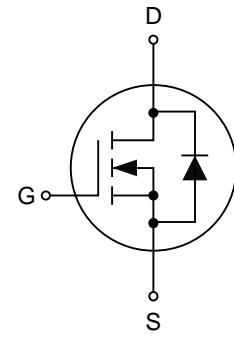
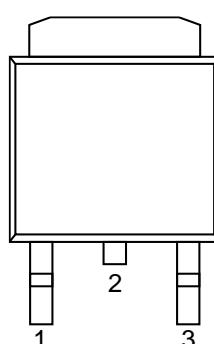
- PWM Application
- Power Management
- Load Switch

#### 1.3 Quick reference

- $BV \geq 60 V$
- $R_{DS(ON)} \leq 5.5 m\Omega @ V_{GS} = 10 V$
- $P_D \leq 69 W$
- $I_D \leq 90 A$

### 2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Gate (G)		
2	Drain (D)		
3	Source (S)		



TO-252  
Top View

**KJ0506KH**

### 3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	Drain-Source Voltage	T <sub>C</sub> =25°C	60	-	V
V <sub>GS</sub>	Gate-Source Voltage	T <sub>C</sub> =25°C	-	±20	V
I <sub>D</sub> *, ***	Drain Current (DC)	T <sub>C</sub> =25°C, V <sub>GS</sub> =10 V	-	90	A
		T <sub>C</sub> =100°C, V <sub>GS</sub> =10 V	-	70	A
I <sub>DM</sub> *	Pulsed Source Current	T <sub>C</sub> =25°C, V <sub>GS</sub> =10 V	-	270	A
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> =25°C	-	69	W
E <sub>AS</sub> *	Single Pulsed Avalanche Energy	V <sub>DD</sub> =30 V, L=0.5 mH	-	313	mJ
T <sub>J</sub> , T <sub>stg</sub>	Operating Junction and Storage Temperature Range		-55	150	°C
R <sub>θJA</sub> **	Thermal Resistance-Junction to Ambient		-	60	°C/W
R <sub>θJC</sub>	Thermal Resistance-Junction to Case		-	1.8	

Notes:

- \* Pulse width ≤ 300 μs, duty cycle ≤ 2%.
- \*\* Surface mounted on 1 in<sup>2</sup> pad area, t ≤ 10 sec.
- \*\*\* Limited by maximum junction temperature.

### 4. Marking Information

Product Name	Marking
KJ0506KH	KJ0506KH XXXXXX

### 5. Ordering Code

Product Name	Package	Reel size	Tape width	Quantity (pcs)
KJ0506KH	TO-252	13"	16 mm	2500

Note: KUAIJIEXIN defines "Green" as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC/JEDEC J-STD-020C).

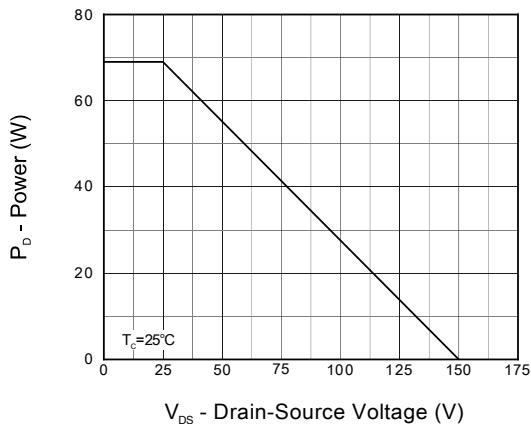
## 6. Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted )

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0 V, I <sub>DS</sub> =250 μA	60	-	-	V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250 μA	2	-	4	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =48 V, V <sub>GS</sub> =0 V	-	-	1	μA
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0 V, V <sub>GS</sub> =±20 V	-	-	±100	nA
R <sub>D(S(ON))<sup>a</sup></sub>	On-State Resistance	V <sub>GS</sub> =10 V, I <sub>DS</sub> =20 A	-	4.5	5.5	mΩ
R <sub>g</sub>	Gate Resistance	Frequency=1.0 MHz	-	2.3	-	Ω
<b>Diode Characteristics</b>						
V <sub>SD<sup>a</sup></sub>	Diode Forward Voltage	I <sub>SD</sub> =20 A, V <sub>GS</sub> =0 V	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>DS</sub> =20 A, V <sub>GS</sub> =0V, dI <sub>SD</sub> /dt=100 A/μs	-	38	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	26	-	nC
<b>Dynamic Characteristics<sup>b</sup></b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0 V, V <sub>DS</sub> =30 V, Frequency=1.0 MHz	-	1480	-	pF
C <sub>oss</sub>	Output Capacitance		-	940	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	103	-	
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =30 V, V <sub>GEN</sub> =10 V, R <sub>G</sub> =6 Ω, I <sub>DS</sub> =20 A	-	13	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	25	-	
t <sub>d(off)</sub>	Turn-off Delay Time		-	29	-	
t <sub>f</sub>	Turn-off Fall Time		-	9	-	
<b>Gate Charge Characteristics<sup>b</sup></b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30 V, V <sub>GS</sub> =0 to 10 V, I <sub>DS</sub> =20 A	-	22	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	11	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	5	-	

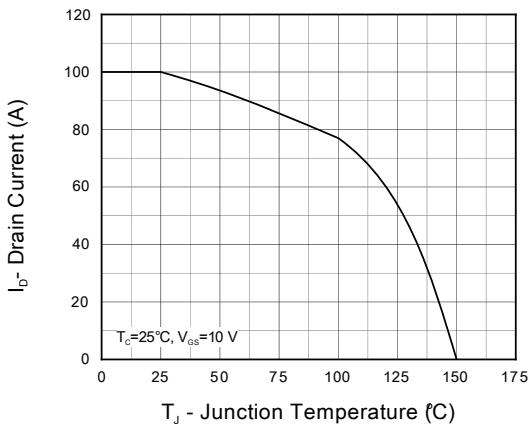
Notes:

- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- b. Guaranteed by design, not subject to production testing.

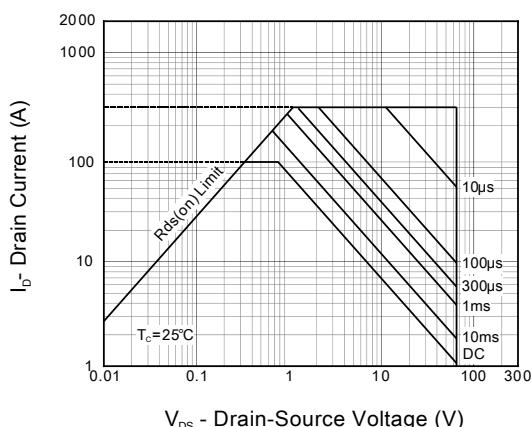
## 7. Typical Characteristics



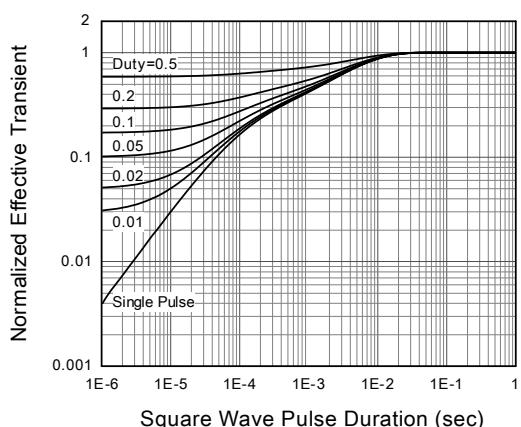
**Figure 1. Output Characteristics**



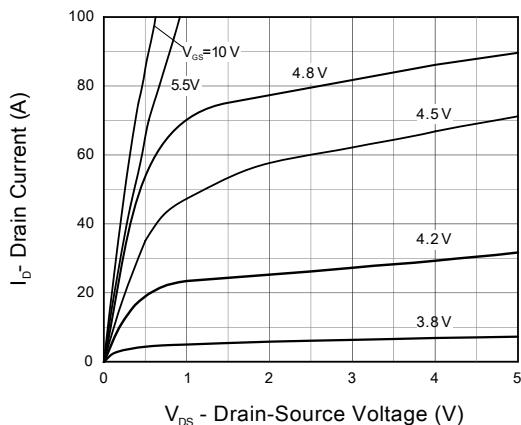
**Figure 2. Current Capability**



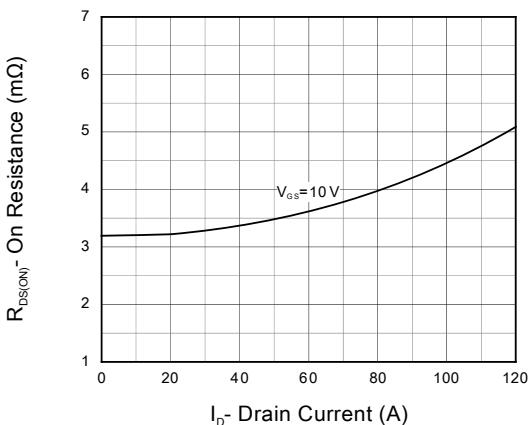
**Figure 3. Safe Operation Area**



**Figure 4. Transient Thermal Impedance**

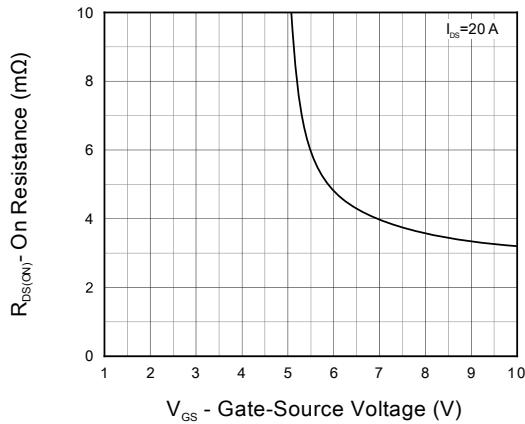


**Figure 5. Output Characteristics**

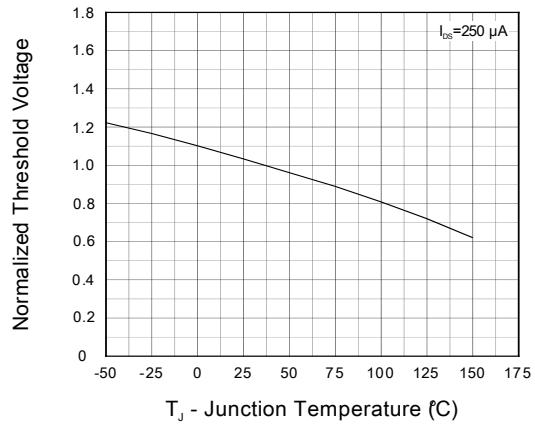


**Figure 6. On Resistance**

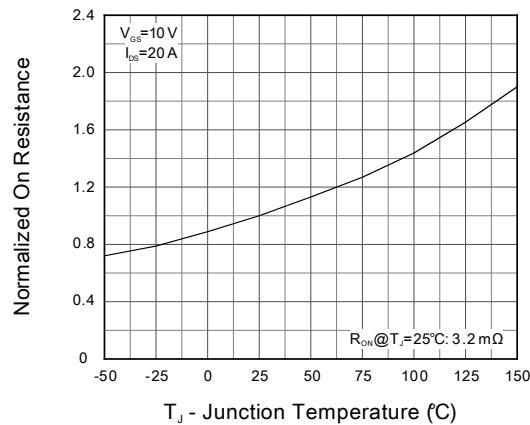
## 7. Typical Characteristics (cont.)



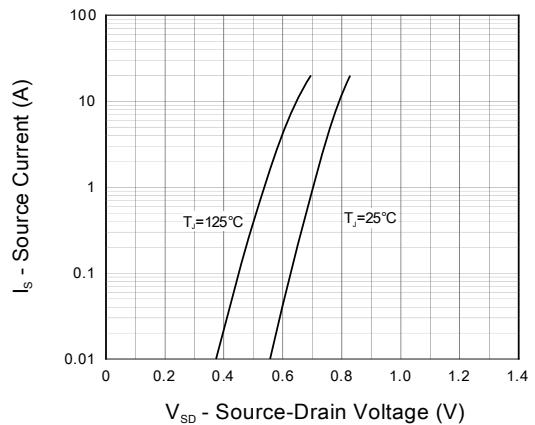
**Figure 7. Transfer Characteristics**



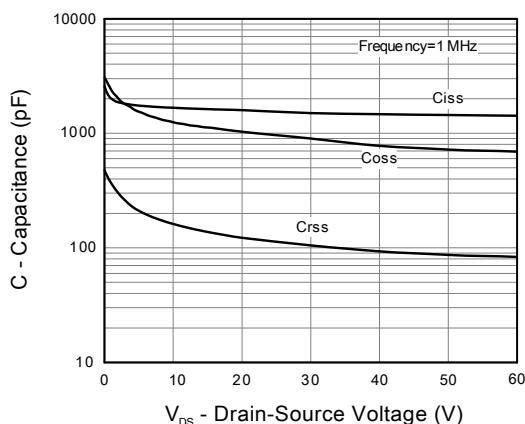
**Figure 8. Normalized Threshold Voltage**



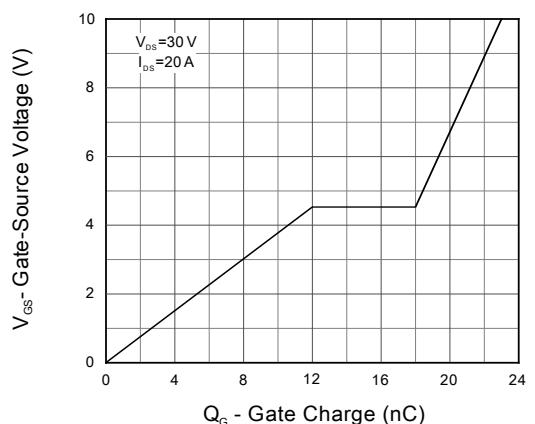
**Figure 9. Normalized On Resistance**



**Figure 10. Diode Forward Current**



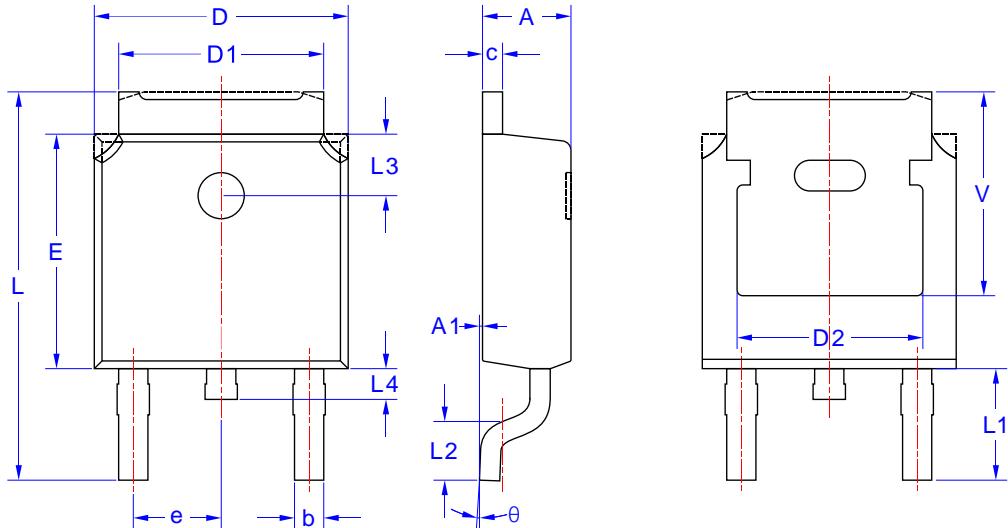
**Figure 11. Capacitance**



**Figure 12. Gate Charge**

## 8. Package Dimensions

TO-252-3L Package



Note: There are two possible shapes for the dashed area.

Symbol	Dimensions in Millimeters	
	MIN	MAX
A	2.200	2.400
A1	0	0.127
b	0.660	0.860
c	0.460	0.580
D	6.500	6.700
D1	5.100	5.460
D2	4.830 REF.	
E	6.000	6.200
e	2.186	2.386
L	9.800	10.400
L1	2.900 REF.	
L2	1.400	1.700
L3	1.600 REF.	
L4	0.600	1.000
V	5.350 REF.	
θ	0°	8°